



承认书

SPECIFICATION FOR APPROVAL

客户 Customer: _/

品牌 Brand: Qiyuan

品名 Description: BT Antenna

规格/型号

Specification

/part no: 3.0dBi@2.4G Built In Ceramic Antenna, 3.2*1.6mm, Single-Stage Bluetooth Ceramic Antenna

日期 Date: 2024.08.05

备注 Remark:

承认签章后请回复一份（或复印件）给我司，其余由贵公司留作存档。如果在签章的承认书（或复印件）回复给我司之前，下了有关此规格产品的订单且又无特别说明，那么我司就确定贵司已完全承认了。Please return one specification or one copy of it with your chop and signature of approval and retain the others for your record. In the event of an order being placed for this part number before the chop and signed with specification (or copy) is returned and without special explanation, it will be assumed that full approval have been given.

客户签字盖章:

拟制/日期 CHECKED/DATE	审核/日期 AUDITOR/DATE	批准/日期 APPROVED/DATE



规格书

客户料号

Customer P/N: /

规格描述

Specification: 3.0dBi@2.4G Built In Ceramic Antenna,
3.2*1.6mm, Single-Stage Bluetooth Ce
ramic Antenna

品名 Description: BT Antenna

供应商 Supplier: Qi Yuan

生产商 Producer: Qi Yuan

备注 Remark:

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拟制/日期 CHECKED/DATE	审核/日期 AUDITOR/DATE	批准/日期 APPROVED/DATE
Zhang Bingxiang 2024.08.05	Wu Qianjin 2024.08.05	Luo Daxun 2024.08.05

[illegible]



PBX3216MC02 Specification

Operating Temp. : -40℃~+85℃

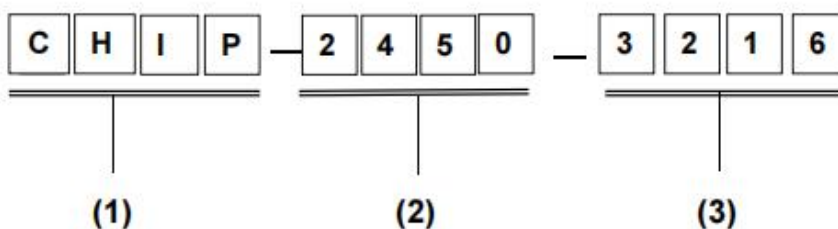
1. FEATURES:

- Light weight, compact
- Wide bandwidth, low cost
- Built-in antenna with high gain

2. APPLICATIONS:

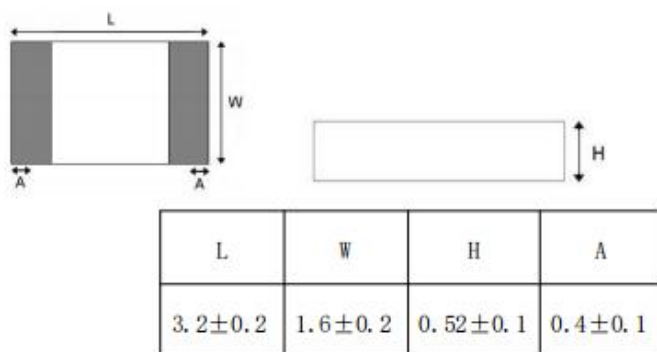
- Bluetooth, Wireless LAN, Mobile TV
- Home RF System, etc

3. PRODUCT IDENTIFICATION



- (1) Product type: Multilayer chip Antenna
(2) Center Frequency: 2450MHz
(3) External Dimensions (L×W) (mm): 3.2*1.6

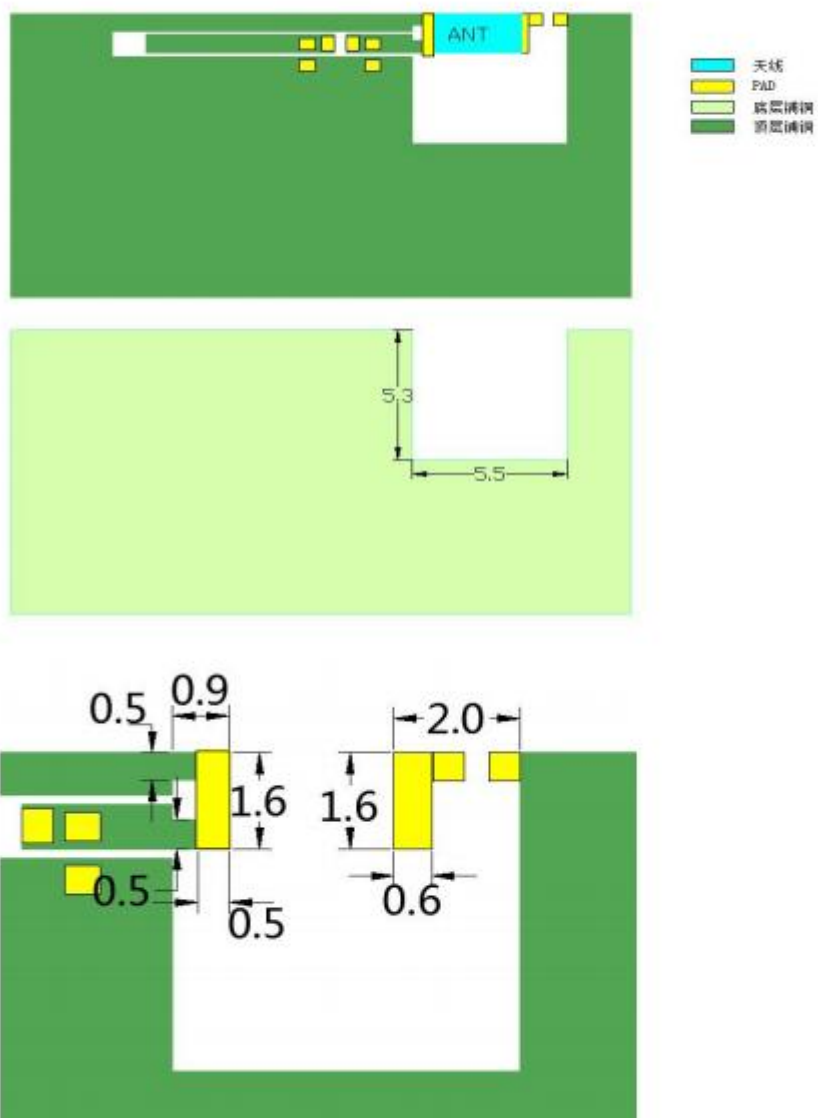
4. SHAPE AND DIMENSIONS:





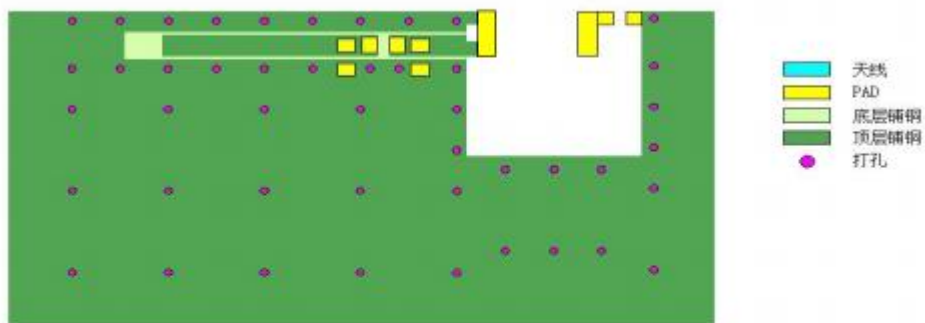
测试板参考尺寸:

单位: mm

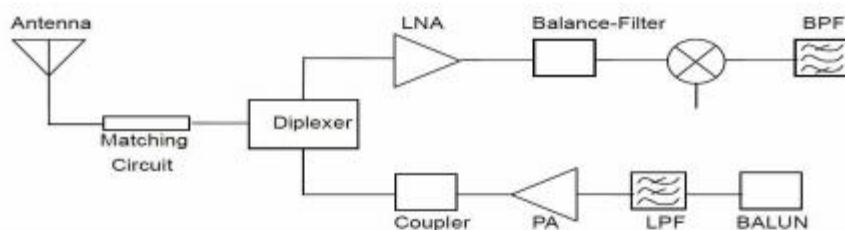




打孔参考示意图



APPLICATION GUIDE



5. SPECIFICATIONS:

测试项目(Test Project)	规格(Specifications)
带宽(Bandwidth)	2400-2483MHz
极化方式(Polarization)	线性极化(Linear)
最大增益(Peak Gain)	2.67dBi
效率(Efficiency)	72.3%
输入阻抗(Input Impedance)	50Ω

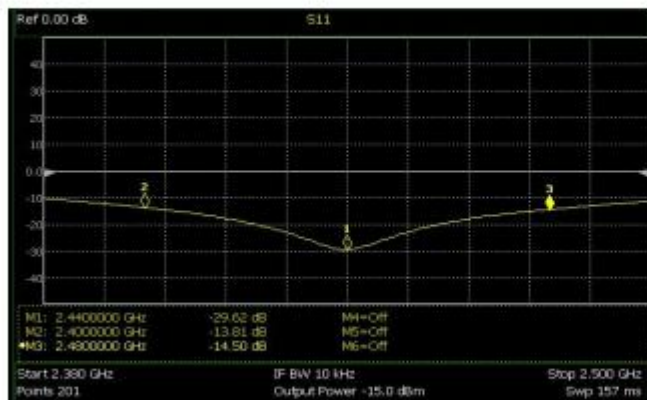
* Test condition: Test board size 90*40 mm

Matching circuit: Pi matching circuit will be required



6. Electrical Characteristics :

回波损耗



驻波比

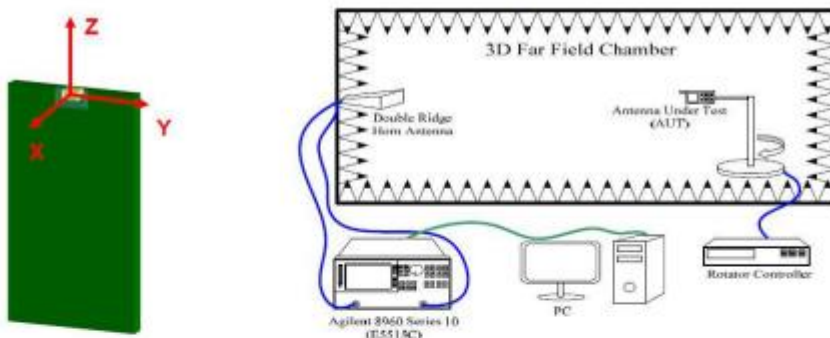


Mark	Frequency	VSWR
1	2400 MHz	1.513
2	2440 MHz	1.068
3	2480 MHz	1.464

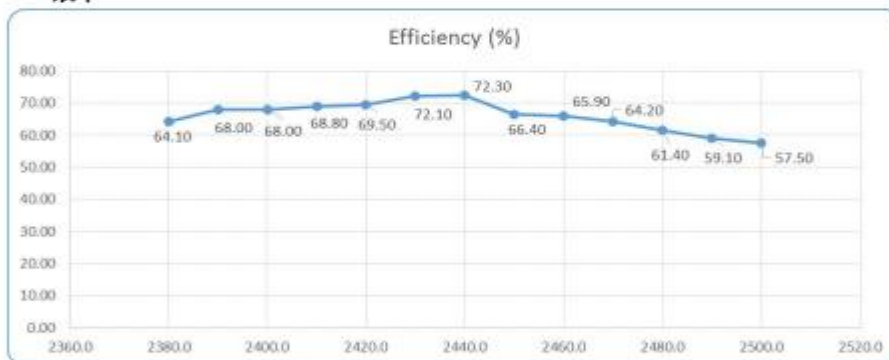


Radiation Pattern

The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator, a standard horn antenna and Vector Network Analyzer is used to collect data.

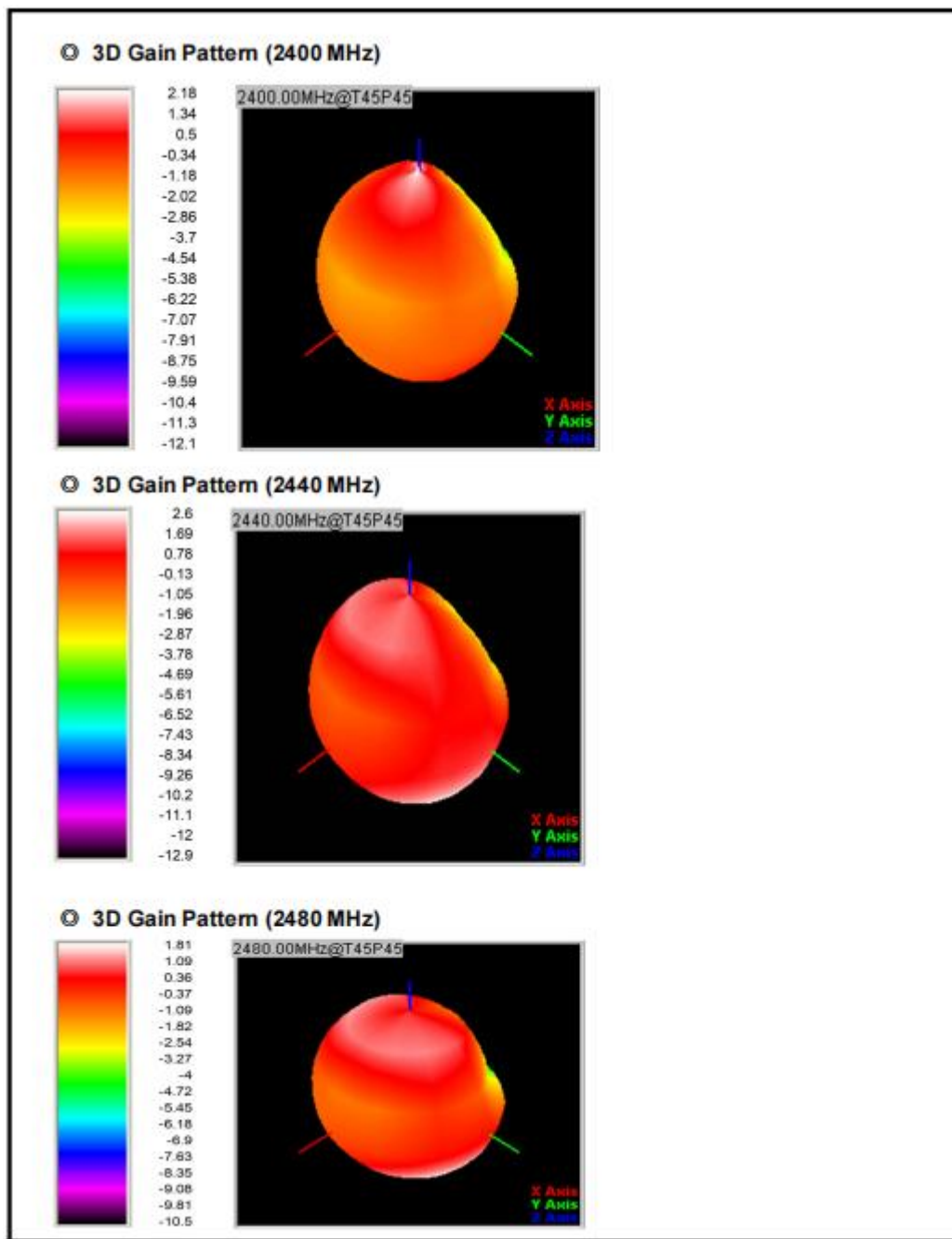


效率



最大增益







7. Environmental Characteristics

(1) Reliability Test

Item	Condition	Specification
Thermal shock	1. 30±3 minutes at -40° C±5° C, 2. Convert to +105° C (5 minutes) 3. 30±3 minutes at +105° C±5° C, 4. Convert to -40° C (5 minutes) 5. Total 100 continuous cycles	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1. Humidity: 85% R.H. 2. Temperature: 85±5° C 3. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	1. Temperature: 150° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Low temperature resistance	1. Temperature: -40° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	1. Solder bath temperature : 260±5℃ 2. Bathing time: 10±1 seconds	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of 245±5℃ for 3±1 seconds.	No apparent damage

(2) Storage Condition

(a) At warehouse:

The temperature should be within 0 ~ 30°C and humidity should be less than 60% RH.

The product should be used within 1 year from the time of delivery.

(b) On board:

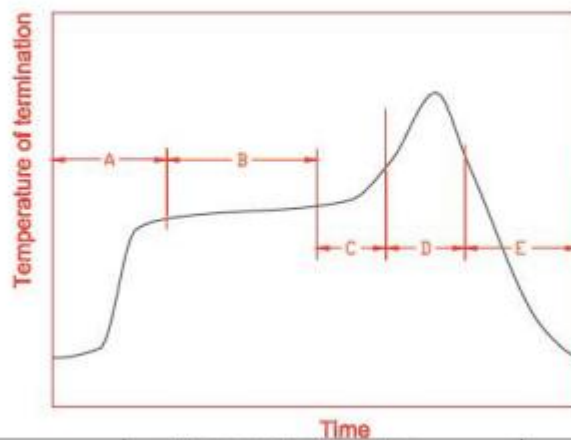
The temperature should be within -40~85°C and humidity should be less than 85% RH.

(3) Operating Temperature Range

Operating temperature range : -40°C to +105°C.



8. Recommended Reflow Soldering



Time			
A	1 st rising temperature	The normal to Preheating temperature	30s to 60s
B	Preheating	140℃ to 160℃	60s to 120s
C	2 nd rising temperature	Preheating to 200℃	20s to 40s
D	Main heating	if 220℃	50s~60s
		if 230℃	40s~50s
		if 240℃	30s~40s
		if 250℃	20s~40s
		if 260℃	20s~40s
E	Regular cooling	200℃ to 100℃	1℃/s ~ 4℃/s

*reference: J-STD-020C

(1) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

- The tip temperature must be less than 350° C for the period within 3 seconds by using soldering gun under 30 W.
- The soldering gun tip shall not touch this product directly.

(2) Soldering Volume

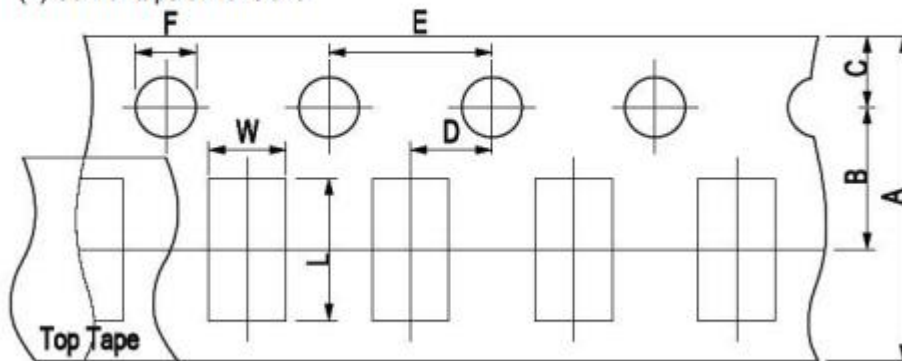
Note that excess of soldering volume will easily get crack the body of this product.



9. Taping Package and Label Marking: (unit: mm)

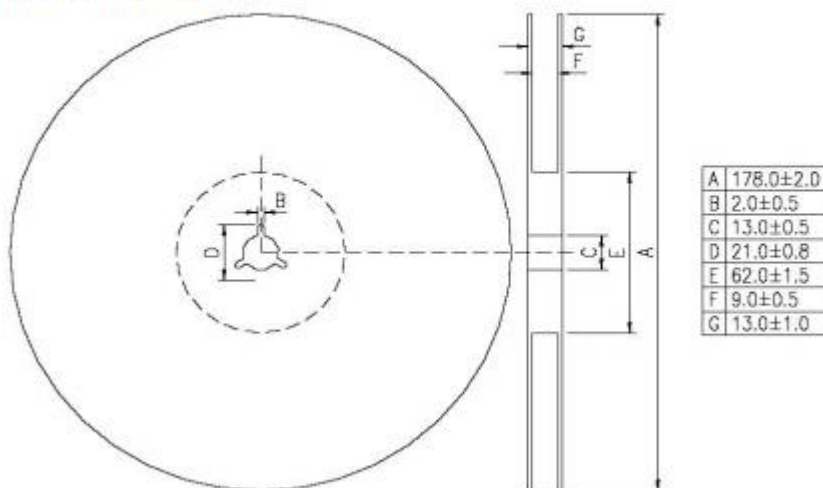
(1) Quantity/Reel: 5000pcs/Reel

(2) Carrier tape dimensions



Type	A	B	C	D	E	F	L	W
2450-21	8.00 ± 0.3	3.50 ± 0.05	1.75 ± 0.1	2.00 ± 0.05	4.00 ± 0.1	1.50 ± 0.1	2.30 ± 0.1	1.55 ± 0.1

(3) Taping reel dimensions



A	178.0 ± 2.0
B	2.0 ± 0.5
C	13.0 ± 0.5
D	21.0 ± 0.8
E	62.0 ± 1.5
F	9.0 ± 0.5
G	13.0 ± 1.0